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Ph.D. thesis (2023-2026)
LGP2 (R. Passas; C. Martin)

Influence of the drying conditions on the surface properties of end-products during Roll to Roll surface functionalisation : comparison between copper and fiber-based strips

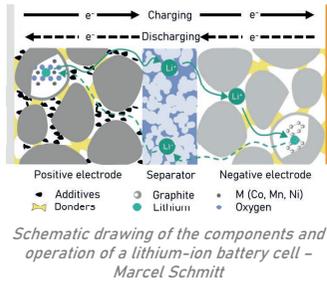
Influence des conditions de séchage sur les propriétés de surface des produits finis lors de la fonctionnalisation de surface Roll to Roll : comparaison entre les bandes à base de cuivre et de fibres

BioChip
MatBio

Context / Objectives

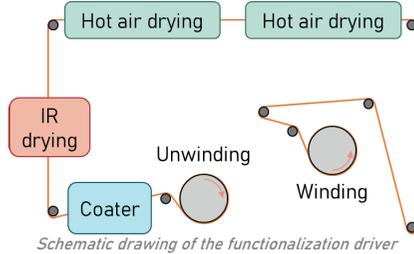
Context : Lithium-ion battery

- Need to store energy produced
- production increasing of electrical cars
- Need to improve the manufacturing process



The electrodes are manufactured by coating an active material on the current collector, copper, for the negative one.

Objectives : Adaptation of a paper functionalization driver for lithium ion battery negative electrode manufacturing.



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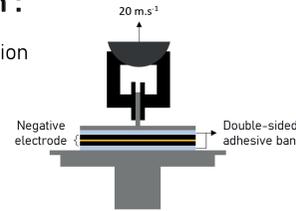
Methods

Slurry characterisation :

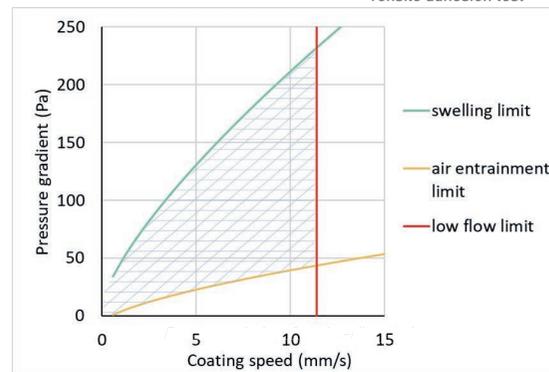
- 2 slurries formulations
- Rheological characterisation
- Surface tension measurement

Copper film characterisation with and without functionalisation :

- Electrical characterisation
- Electrochemical characterisation
- Surface characterisation
- Thermal characterisation
- Mechanical characterisation
- Adhesion to the substrate



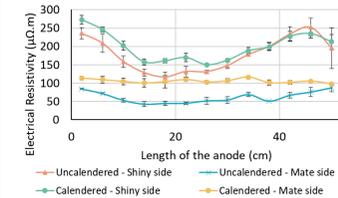
Slot die coating :



Copper temperature simulation on the driver.

Results

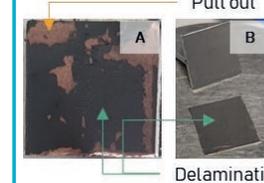
Electrical resistivity :



- The glossy side is less conductive than the matte side.
- Calendering does not improve the conductivity of the layer.
- Presence of edge effect for the glossy side.

Electrical resistance along the entire length of a negative electrode (cross direction of production)

Adhesion to the substrate :

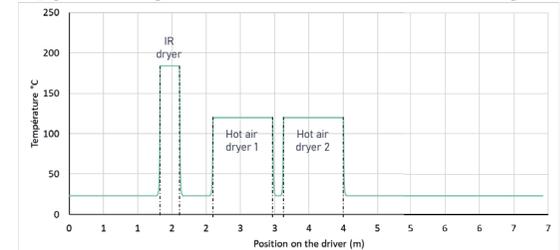


	Pull-out	Delamination
Uncalendered	→	→
Calendered	X	→

- Uncalendered electrodes : shiny side is more adhesive.

Electrode delamination after tensile adhesion test on A) uncalendered and B) calendered electrode

Copper temperature simulation on the pilote



Modeling the evolution of copper temperature in a steady-state condition throughout the driver.